Adwill®
will give you the Advantage

Pressurized Curing System

RAD-9100-450

Outline

–Pressurized curing system used for Adwill LE Tape for substrates. The heat and pressure curing reduces voids from occuring between Adwill LE Tape and substrate, thus improving die bonding reliability. This system eliminates the substrate baking process prior to die bonding.

Suitable Tape ·Dicing die bonding tape : Adwill LE Tape

Facility

Power Supply	Voltage	: AC200-240V (±10%)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 4.6kW
Air Supply	Air pressure	: 0.98MPa
	Air consumption	: >165L/cycle

Applicable Wafer Size

N/A

Size

Width : 995mm
Depth : 1,200mm
Height : 1,520mm
(excluding the signal tower)

Weight

500kg

Effective Height

Max. 270mm

Maximum Pressure

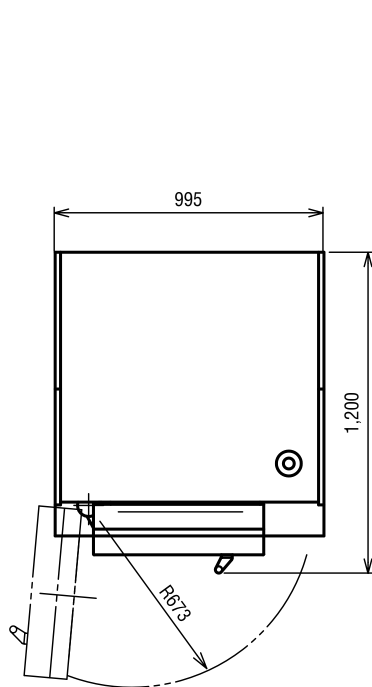
1.0MPa

Maximum Temperature

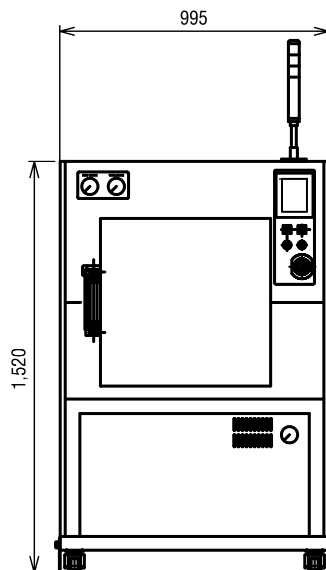
200℃

External View

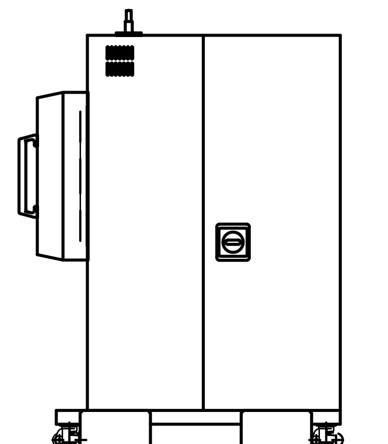
Unit:mm



Top View



Front View



Right Side View

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